

WHAT IS CLAIMED IS:

1. A method for manufacturing electron emitting devices each of which is provided with electrodes formed on a substrate and an
5 electroconductive thin film connected between said electrodes and having an electron emitting region, said method comprising the steps of:

subjecting said substrate formed with said electrodes to a hydrophobic process using a silane
10 coupling agent which contains two or more acetoxy groups in a molecule; and

thereafter dispensing liquid droplets containing material for forming said
electroconductive thin film onto said electrodes.

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2. The method for manufacturing electron emitting devices according to claim 1, wherein said step of dispensing the liquid droplets is performed by an ink jet method.

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3. A method for manufacturing electron emitting devices by using the steps of dispensing liquid droplets containing material for forming an electroconductive thin film to an area between
25 opposing electrodes formed on a substrate, performing a heating and baking process to form said

electroconductive thin film connected to both of said electrodes, and thereafter forming an electron emitting region in said electroconductive thin film,

wherein said substrate formed with said
5 electrodes is subjected to a hydrophobic process using a silane coupling agent which contains two or more acetoxy groups in a molecule; and thereafter said liquid droplets are dispensed onto said electrodes.

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4. The method for manufacturing electron emitting devices according to claim 3, wherein said silane coupling agent is diacetoxydimethylsilane.

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5. The method for manufacturing electron emitting devices according to claim 3, wherein said step of dispensing the liquid droplets is performed by an ink jet method.

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6. A method for manufacturing electron emitting devices each of which is provided with electrodes formed on a substrate and an electroconductive thin film connected between said electrodes and having an electron emitting region, said method comprising

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steps of:

subjecting said substrate formed with said

electrodes to a hydrophobic process using a mixture of two or more silane coupling agents having different hydrolysis groups; and

thereafter dispensing liquid droplets
5 containing material for forming said
electroconductive thin film onto said electrodes.

7. The method for manufacturing electron
emitting devices according to claim 6, wherein said
10 step of dispensing the liquid droplets is performed
by an ink jet method.

8. The method for manufacturing electron
emitting devices according to claim 6, wherein one of
15 said two or more silane coupling agents is a silane
coupling agent which contains two or more acetoxy
groups in a molecule.

9. The method for manufacturing electron
20 emitting devices according to claim 8, wherein said
silane coupling agent which contains two or more
acetoxy groups in a molecule is
diacetoxydimethylsilane.

25 10. The method for manufacturing electron
emitting devices according to claim 6, wherein one of

said two or more silane coupling agents contains an acetoxy group in a molecule and another contains an ethoxy group in a molecule.

5 11. A method for manufacturing electron
emitting devices by using the steps of dispensing
liquid droplets containing material for forming an
electroconductive thin film to an area between
opposing electrodes formed on a substrate, performing
10 a heating and baking process to form said
electroconductive thin film connected to both of said
electrodes, and thereafter forming an electron
emitting region in said electroconductive thin film,
 wherein said substrate formed with said
15 electrodes is subjected to a hydrophobic process
using a mixture of two or more silane coupling agents
having different hydrolysis groups, and thereafter
said liquid droplets are dispensed onto said
electrodes.

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 12. The method for manufacturing electron
emitting devices according to claim 11, wherein one
of said two or more silane coupling agents is a
silane coupling agent which contains two or more
25 acetoxy groups in a molecule.

13. The method for manufacturing electron emitting devices according to claim 12, wherein said silane coupling agent which contains two or more acetoxy groups in a molecule is
5 diacetoxymethylsilane.

14. The method for manufacturing electron emitting devices according to claim 11, wherein one of said two or more silane coupling agents contains
10 an acetoxy group in a molecule and another contains an ethoxy group in a molecule.

15. The method for manufacturing electron emitting devices according to claim 11, wherein
15 dispensing the liquid droplets is performed by an ink jet method.

16. A method for manufacturing an image display apparatus comprising a step of dispensing liquid
20 droplets which contains material for forming an image display member by an ink jet method, to a substrate subjected to a hydrophobic process using a silane coupling agent which contains two or more acetoxy groups in a molecule.

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17. A method for manufacturing an image display

apparatus comprising a step of dispensing liquid
droplets which contains material for forming an image
display member by an ink jet method, to a substrate
subjected to a hydrophobic process using a mixture of
5 two or more silane coupling agents having different
hydrolysis groups.